



**Note:**

**1. Material:**

- 1.1 Housing: High temperature thermoplastic with g.f, UL94v-0
- 1.2 Contact: copper alloy, t=0.20mm
- 1.3 Shell: copper alloy, t=0.25mm

**2. Specification:**

- 2.1 Current rating: 1A Max
- 2.2 Dielectric withstanding voltage: 100V(AC) for 1 min.
- 2.3 Contact resistance: 50mΩ Max.
- 2.4 Insulation resistance: 100mΩ min.
- 2.5 Tatal mating force: 3.57 Kg Max.
- 2.6 Total unmating force: 1.0 Kg Min. 0.81~2.05 Kg Min. after 10,000 insertion/extraction cycles
- 2.7 Temperature range: -30° C~80° C

ITEM	PAPT NAME	QTY	MATERIAL	FINISHING
③	Shell	1	SUS304R-1/2H	Ni Plating T=0.3mm (3u)
②	Terminal	5	Phosphor Bronze C5191R-EH	Au/Ni Plating T=0.2mm (1u)
①	Housing	1	HI-TEMP.PLASIC UL 94V-0	BLACK

					DSND	DATE	SCALE: N/A	MODEL TYPE:		
					DWN	DATE	VIEW:	MICRO USB		
					CHKD	DATE	UNIT: mm	PART NO.:		
					APPD	DATE	SIZE: A4	DWG NO.:		
					KOSOD TECHNOLOGY CO., LTD			U-E-M5SS-W-0		
					UNSPECIFIED TOLERANCES			WEIGHT	SHEET	REVISION
								1.0g	1/1	A0

MARK	DESCRIPTION	DATE	REVISED	APPROVED	ANGLAR	±5°
ΔX					L ≤ 4	±0.2
ΔX					4 < L ≤ 16	±0.3
ΔX					16 < L ≤ 63	±0.4
					L > 63	±0.5